# BCP54; BCX54; BC54PA

# 45 V, 1 A NPN medium power transistors Rev. 8 — 21 October 2011

Product data sheet

#### 1. **Product profile**

#### 1.1 General description

NPN medium power transistor series in Surface-Mounted Device (SMD) plastic packages.

Table 1. **Product overview** 

Type number[1]	Package	Package		
	Nexperia	JEITA	JEDEC	
BCP54	SOT223	SC-73	-	BCP51
BCX54	SOT89	SC-62	TO-243	BCX51
BC54PA	SOT1061	-	-	BC51PA

<sup>[1]</sup> Valid for all available selection groups.

#### 1.2 Features and benefits

- High current
- Three current gain selections
- High power dissipation capability
- Exposed heatsink for excellent thermal and electrical conductivity (SOT89, SOT1061)
- Leadless very small SMD plastic package with medium power capability (SOT1061)
- AEC-Q101 qualified

#### 1.3 Applications

- Linear voltage regulators
- Low-side switches
- Battery-driven devices
- Power management
- MOSFET drivers
- Amplifiers

#### 1.4 Quick reference data

Table 2. Quick reference data

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$V_{CEO}$	collector-emitter voltage	open base	-	-	45	V
I <sub>C</sub>	collector current		-	-	1	Α
I <sub>CM</sub>	peak collector current	single pulse; $t_p \le 1 \text{ ms}$	-	-	2	Α
h <sub>FE</sub>	DC current gain	$V_{CE} = 2 \text{ V}; I_{C} = 150 \text{ mA}$	[ <u>1</u> ] 63	-	250	
	h <sub>FE</sub> selection -10	$V_{CE} = 2 \text{ V}; I_{C} = 150 \text{ mA}$	[ <u>1</u> ] 63	-	160	
	h <sub>FE</sub> selection -16	$V_{CE} = 2 \text{ V}; I_{C} = 150 \text{ mA}$	<u>[1]</u> 100	-	250	

<sup>[1]</sup> Pulse test:  $t_p \le 300 \ \mu s$ ;  $\delta = 0.02$ .



# 2. Pinning information

Table 3. **Pinning** Simplified outline **Graphic symbol** Pin Description **SOT223** 1 base 2, 4 2 collector 3 emitter 4 collector sym016 **SOT89** 1 emitter 2 collector 3 base SOT1061 1 base 3 | 2 emitter 3 collector sym021 Transparent top view

# 3. Ordering information

Table 4. Ordering information

Type number[1]	Package							
	Name	Description	Version					
BCP54	SC-73	plastic surface-mounted package with increased heatsink; 4 leads	SOT223					
BCX54	SC-62	plastic surface-mounted package; exposed die pad for good heat transfer; 3 leads	SOT89					
BC54PA	HUSON3	plastic thermal enhanced ultra thin small outline package; no leads; 3 terminals; body 2 $\times$ 2 $\times$ 0.65 mm	SOT1061					

<sup>[1]</sup> Valid for all available selection groups.

# 4. Marking

Table 5. Marking codes

•	
Type number	Marking code
BCP54	BCP54
BCP54-10	BCP54/10
BCP54-16	BCP54/16
BCX54	BA
BCX54-10	BC
BCX54-16	BD
BC54PA	AT
BC54-10PA	BF
BC54-16PA	BG

# 5. Limiting values

Table 6. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CBO}$	collector-base voltage	open emitter	-	45	V
$V_{CEO}$	collector-emitter voltage	open base	-	45	V
$V_{EBO}$	emitter-base voltage	open collector	-	5	V
I <sub>C</sub>	collector current		-	1	Α
I <sub>CM</sub>	peak collector current	single pulse; $t_p \le 1 \text{ ms}$	-	2	Α
I <sub>B</sub>	base current		-	0.3	Α
I <sub>BM</sub>	peak base current	single pulse; $t_p \le 1 \text{ ms}$	-	0.3	Α
P <sub>tot</sub>	total power dissipation	$T_{amb} \le 25  ^{\circ}C$			
	BCP54		<u>[1]</u> -	0.65	W
			[2]	1.00	W
			[3]	1.35	W
	BCX54		<u>[1]</u> -	0.50	W
			[2]	0.95	W
			[3]	1.35	W
	BC54PA		<u>[1]</u> -	0.42	W
			[2]	0.83	W
			[3]	1.10	W
			[4]	0.81	W
			<u>[5]</u> _	1.65	W
Tj	junction temperature		-	150	°C
T <sub>amb</sub>	ambient temperature		-55	+150	°C
T <sub>stg</sub>	storage temperature		-65	+150	°C

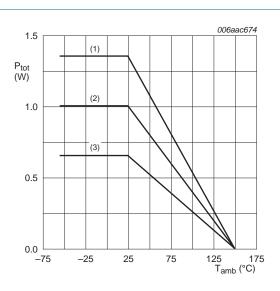
<sup>[1]</sup> Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

<sup>[2]</sup> Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 1 cm<sup>2</sup>.

<sup>[3]</sup> Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 6 cm<sup>2</sup>.

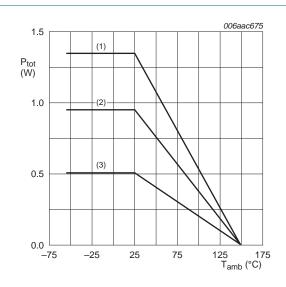
<sup>[4]</sup> Device mounted on an FR4 PCB, 4-layer copper, tin-plated and standard footprint.

<sup>[5]</sup> Device mounted on an FR4 PCB, 4-layer copper, tin-plated, mounting pad for collector 1 cm<sup>2</sup>.



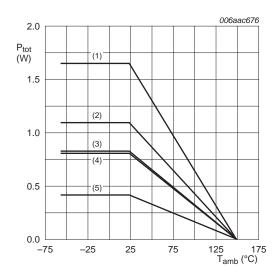
- (1) FR4 PCB, mounting pad for collector 6 cm<sup>2</sup>
- (2) FR4 PCB, mounting pad for collector 1 cm<sup>2</sup>
- (3) FR4 PCB, standard footprint

Fig 1. Power derating curves SOT223



- (1) FR4 PCB, mounting pad for collector 6 cm<sup>2</sup>
- (2) FR4 PCB, mounting pad for collector 1 cm<sup>2</sup>
- (3) FR4 PCB, standard footprint

Fig 2. Power derating curves SOT89



- (1) FR4 PCB, 4-layer copper, mounting pad for collector 1 cm<sup>2</sup>
- (2) FR4 PCB, single-sided copper, mounting pad for collector 6 cm<sup>2</sup>
- (3) FR4 PCB, single-sided copper, mounting pad for collector 1 cm<sup>2</sup>
- (4) FR4 PCB, 4-layer copper, standard footprint
- (5) FR4 PCB, single-sided copper, standard footprint

Fig 3. Power derating curves SOT1061

### 6. Thermal characteristics

Table 7. Thermal characteristics

Table 7.	I nermai characteristics					
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air				
	BCP54		<u>[1]</u> -	-	192	K/W
			[2] _	-	125	K/W
			[3] _	-	93	K/W
	BCX54		<u>[1]</u> -	-	250	K/W
			[2] _	-	132	K/W
			[3] _	-	93	K/W
	BC54PA		[1] _	-	298	K/W
			[2] _	-	151	K/W
			[3] _	-	114	K/W
			[4] _	-	154	K/W
			[5] _	-	76	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point					
	BCP54		-	-	16	K/W
	BCX54		-	-	16	K/W
	BC54PA	BC54PA			20	K/W

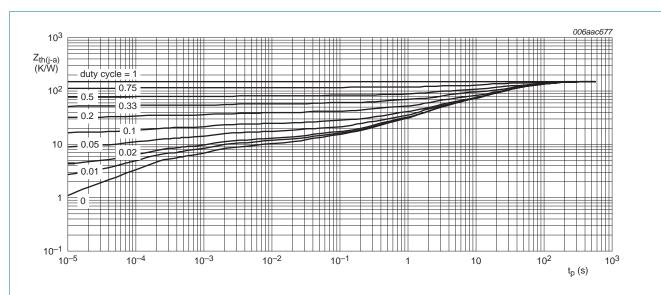
<sup>[1]</sup> Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

<sup>[2]</sup> Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 1 cm<sup>2</sup>.

<sup>[3]</sup> Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 6 cm<sup>2</sup>.

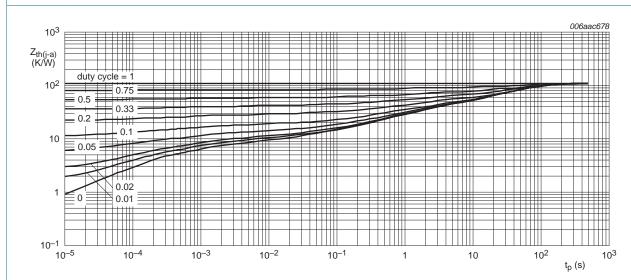
<sup>[4]</sup> Device mounted on an FR4 PCB, 4-layer copper, tin-plated and standard footprint.

<sup>[5]</sup> Device mounted on an FR4 PCB, 4-layer copper, tin-plated, mounting pad for collector 1 cm<sup>2</sup>.



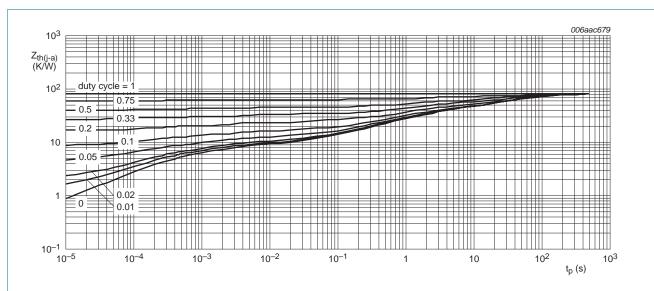
FR4 PCB, standard footprint

Fig 4. Transient thermal impedance from junction to ambient as a function of pulse duration for SOT223; typical values



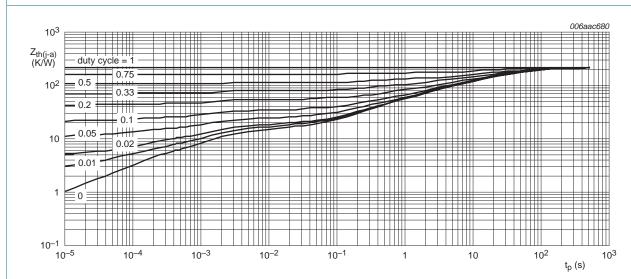
FR4 PCB, mounting pad for collector 1 cm<sup>2</sup>

Fig 5. Transient thermal impedance from junction to ambient as a function of pulse duration for SOT223; typical values



FR4 PCB, mounting pad for collector 6 cm<sup>2</sup>

Fig 6. Transient thermal impedance from junction to ambient as a function of pulse duration for SOT223; typical values



FR4 PCB, standard footprint

Fig 7. Transient thermal impedance from junction to ambient as a function of pulse duration for SOT89; typical values

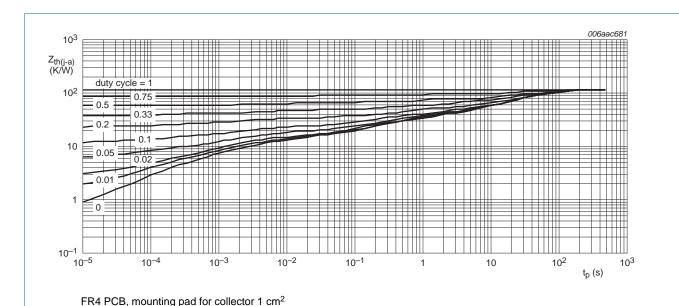
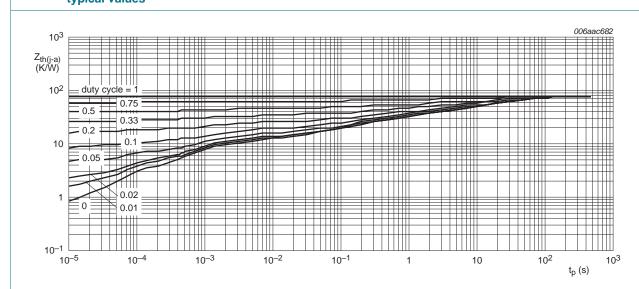


Fig 8. Transient thermal impedance from junction to ambient as a function of pulse duration for SOT89; typical values



FR4 PCB, mounting pad for collector 6 cm<sup>2</sup>

Fig 9. Transient thermal impedance from junction to ambient as a function of pulse duration for SOT89; typical values

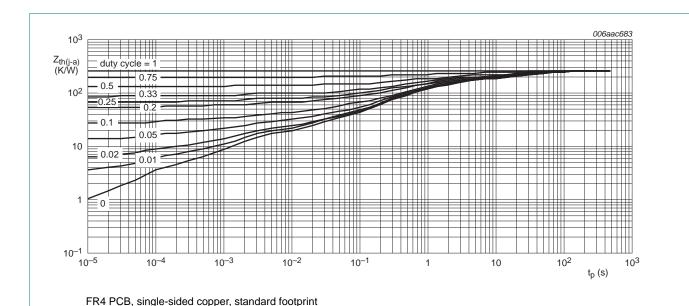
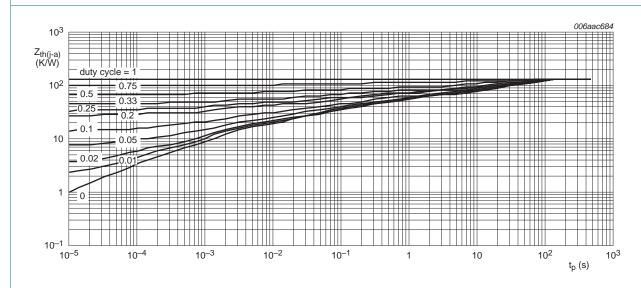


Fig 10. Transient thermal impedance from junction to ambient as a function of pulse duration for SOT1061; typical values

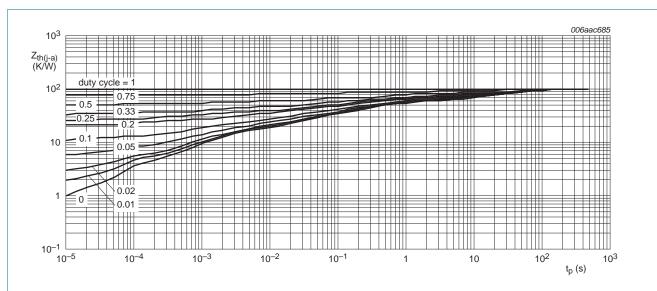


FR4 PCB, single-sided copper, mounting pad for collector 1 cm<sup>2</sup>

Fig 11. Transient thermal impedance from junction to ambient as a function of pulse duration for SOT1061;

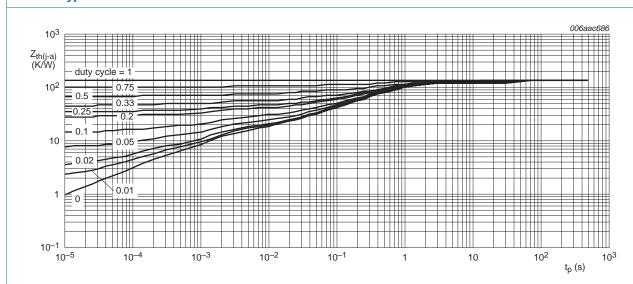
BCP54\_BCX54\_BC54PA

typical values



FR4 PCB, single-sided copper, mounting pad for collector 6 cm<sup>2</sup>

Fig 12. Transient thermal impedance from junction to ambient as a function of pulse duration for SOT1061; typical values



FR4 PCB, 4-layer copper, standard footprint

Fig 13. Transient thermal impedance from junction to ambient as a function of pulse duration for SOT1061; typical values

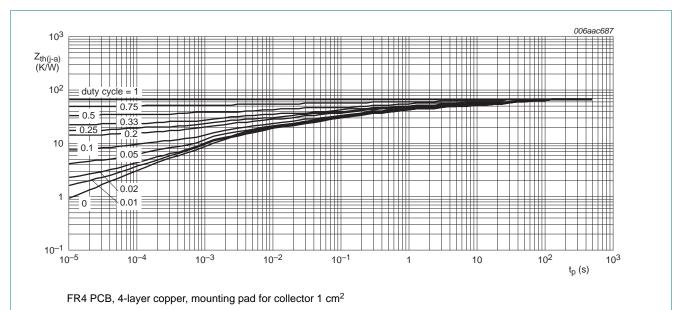


Fig 14. Transient thermal impedance from junction to ambient as a function of pulse duration for SOT1061; typical values

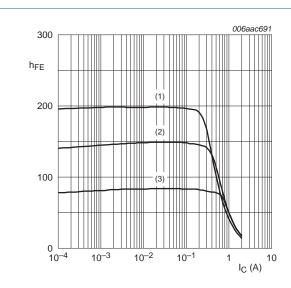
### 7. Characteristics

Table 8. Characteristics

 $T_{amb} = 25$  °C unless otherwise specified.

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
I <sub>CBO</sub>	collector-base cut-off	$V_{CB} = 30 \text{ V}; I_{E} = 0 \text{ A}$		-	-	100	nΑ
	current	$V_{CB} = 30 \text{ V}; I_E = 0 \text{ A};$ $T_j = 150 \text{ °C}$		-	-	10	μΑ
I <sub>EBO</sub>	emitter-base cut-off current	$V_{EB} = 5 \text{ V}; I_{C} = 0 \text{ A}$		-	-	100	nA
h <sub>FE</sub>	DC current gain	V <sub>CE</sub> = 2 V					
		$I_C = 5 \text{ mA}$	<u>[1]</u>	63	-	-	
		$I_C = 150 \text{ mA}$	<u>[1]</u>	63	-	250	
		$I_C = 500 \text{ mA}$	<u>[1]</u>	40	-	-	
	DC current gain	V <sub>CE</sub> = 2 V					
	h <sub>FE</sub> selection -10	$I_C = 150 \text{ mA}$	<u>[1]</u>	63	-	160	
	h <sub>FE</sub> selection -16	$I_C = 150 \text{ mA}$	<u>[1]</u>	100	-	250	
V <sub>CEsat</sub>	collector-emitter saturation voltage	$I_C = 500 \text{ mA}; I_B = 50 \text{ mA}$	[1]	-	-	0.5	V
$V_{BE}$	base-emitter voltage	$V_{CE} = 2 \text{ V}; I_{C} = 500 \text{ mA}$	<u>[1]</u>	-	-	1	V
C <sub>c</sub>	collector capacitance	$V_{CB} = 10 \text{ V}; I_E = i_e = 0 \text{ A};$ f = 1 MHz		-	6	-	pF
f <sub>T</sub>	transition frequency	$V_{CE} = 5 \text{ V; } I_{C} = 50 \text{ mA;}$ f = 100 MHz		100	180	-	MHz

<sup>[1]</sup> Pulse test:  $t_p \le 300 \ \mu s; \ \delta = 0.02.$ 



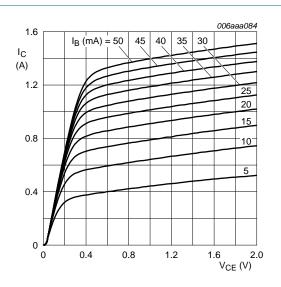
 $V_{CE} = 2 V$ 

(1)  $T_{amb} = 100 \, ^{\circ}C$ 

(2)  $T_{amb} = 25 \, ^{\circ}C$ 

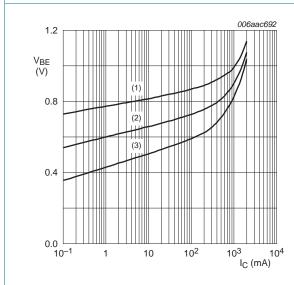
(3)  $T_{amb} = -55 \, ^{\circ}C$ 

Fig 15. DC current gain as a function of collector current; typical values



T<sub>amb</sub> = 25 °C

Fig 16. Collector current as a function of collector-emitter voltage; typical values



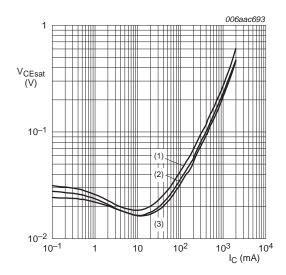
 $V_{CE} = 2 V$ 

(1)  $T_{amb} = -55 \, ^{\circ}C$ 

(2)  $T_{amb} = 25 \, ^{\circ}C$ 

(3)  $T_{amb} = 100 \, ^{\circ}C$ 

Fig 17. Base-emitter voltage as a function of collector current; typical values



 $I_{\rm C}/I_{\rm B} = 10$ 

(1)  $T_{amb} = 100 \, ^{\circ}C$ 

(2)  $T_{amb} = 25 \, ^{\circ}C$ 

(3)  $T_{amb} = -55 \, ^{\circ}C$ 

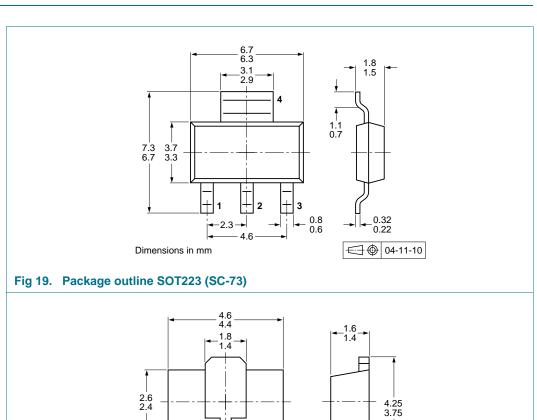
Fig 18. Collector-emitter saturation voltage as a function of collector current; typical values

# 8. Test information

### 8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

# 9. Package outline



0.48 0.35

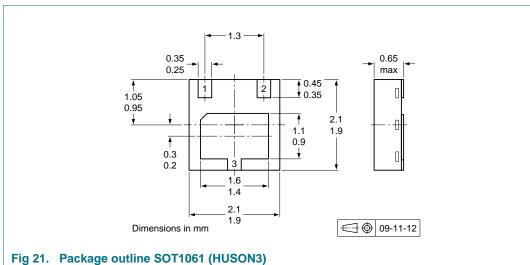
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Fig 20. Package outline SOT89 (SC-62/TO-243)

Dimensions in mm

0.53

-1.5



# 10. Packing information

**Packing methods** Table 9.

The indicated -xxx are the last three digits of the 12NC ordering code.[1]

Туре	Package	·		Packing quantity		
number[2]				1000	3000	4000
BCP54	SOT223	8 mm pitch, 12 mm tape and reel		-115	-	-135
BCX54 SOT89		8 mm pitch, 12 mm tape and reel; T1	[3]	-115	-	-135
		8 mm pitch, 12 mm tape and reel; T3	[4]	-146	-	-
BC54PA	SOT1061	4 mm pitch, 8 mm tape and reel		-	-115	-

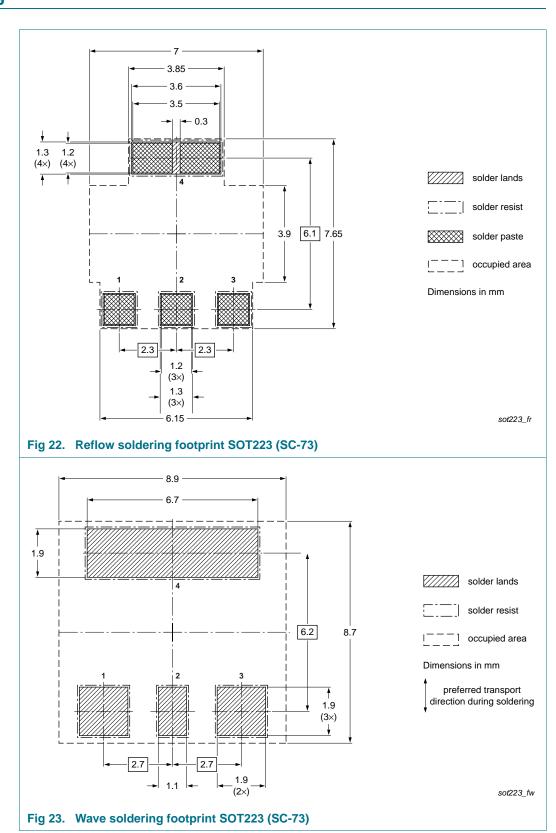
<sup>[1]</sup> For further information and the availability of packing methods, see Section 14.

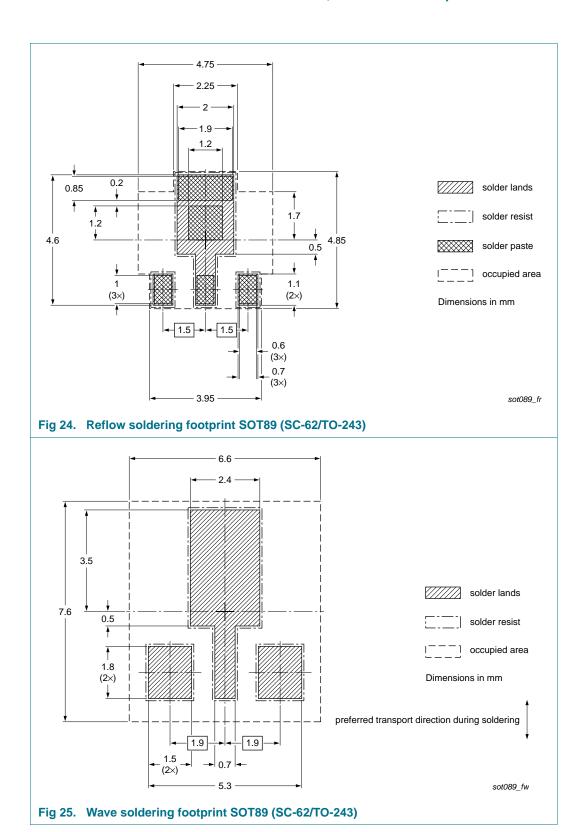
Valid for all available selection groups.

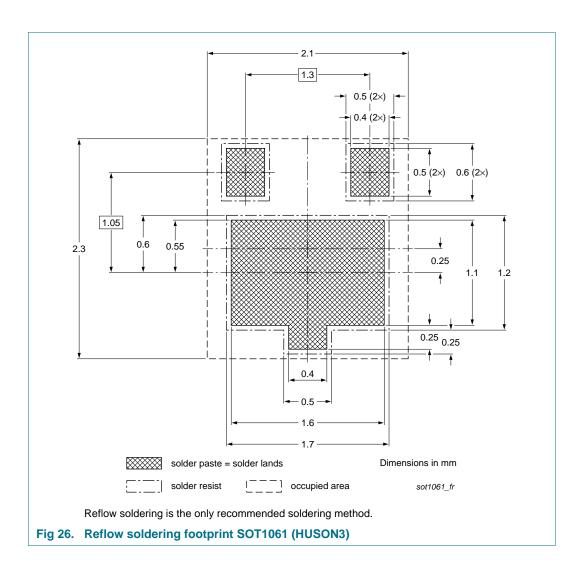
T1: normal taping

<sup>[4]</sup> T3: 90° rotated taping

# 11. Soldering







# 12. Revision history

Table 10. Revision history

Table for Reviews incomme					
Document ID	Release date	Data sheet status	Change notice	Supersedes	
BCP54_BCX54_BC54PA v.8	20111021	Product data sheet	-	BC635_BCP54_BCX54 v.7	
Modifications:	<ul> <li>Type number</li> </ul>	er removed: BC635			
	<ul> <li>Type number</li> </ul>	ers added: BC54PA, BC54	-10PA and BC54-1	16PA	
	<ul> <li>Section 1 "F</li> </ul>	Product profile": updated			
	<ul> <li>Section 2 "F</li> </ul>	Pinning information": updat	ed		
<ul> <li><u>Table 6</u> and <u>7</u>: updated according to latest measurements</li> </ul>					
	• <u>Figure 1</u> , <u>2</u> ,	4, 5, 7 to 9, 15, 17 and 18	: updated		
	• Figure 3, 6,	10 to 14: added			
	<ul> <li>Section 8 "7</li> </ul>	Test information": added			
	<ul> <li>Section 10 '</li> </ul>	"Packing information": upda	ated		
	<ul> <li>Section 11 "</li> </ul>	<u>'Soldering"</u> : added			
	<ul> <li>Section 13 '</li> </ul>	"Legal information": update	ed		
BC635_BCP54_BCX54 v.7	20070604	Product data sheet	-	BC635_BCP54_BCX54 v.6	
BC635_BCP54_BCX54 v.6	20050225	Product data sheet	CPCN2004050	BC635_637_639 v.4	
			29	BCP54_55_56 v.5	
				BCX54_55_56 v.4	
BC635_637_639 v.4	20011010	Product specification	-	BC635_637_639 v.3	
BCP54_55_56 v.5	20030206	Product specification	-	BCP54_55_56 v.4	
BCX54_55_56 v.4	20011010	Product specification	-	BCX54_55_56 v.3	

## 13. Legal information

#### 13.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions"
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nexperia.com.

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Limiting values — Stress above one or more limiting values (as defined in the Absolute Maximum Ratings System of IEC 60134) will cause permanent damage to the device. Limiting values are stress ratings only and (proper) operation of the device at these or any other conditions above those given in the Recommended operating conditions section (if present) or the Characteristics sections of this document is not warranted. Constant or repeated exposure to limiting values will permanently and irreversibly affect the quality and reliability of the device.

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BCP54\_BCX54\_BC54PA

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#### 13.4 Trademarks

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### 14. Contact information

For more information, please visit: http://www.nexperia.com

For sales office addresses, please send an email to: salesaddresses@nexperia.com

# 15. Contents

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